

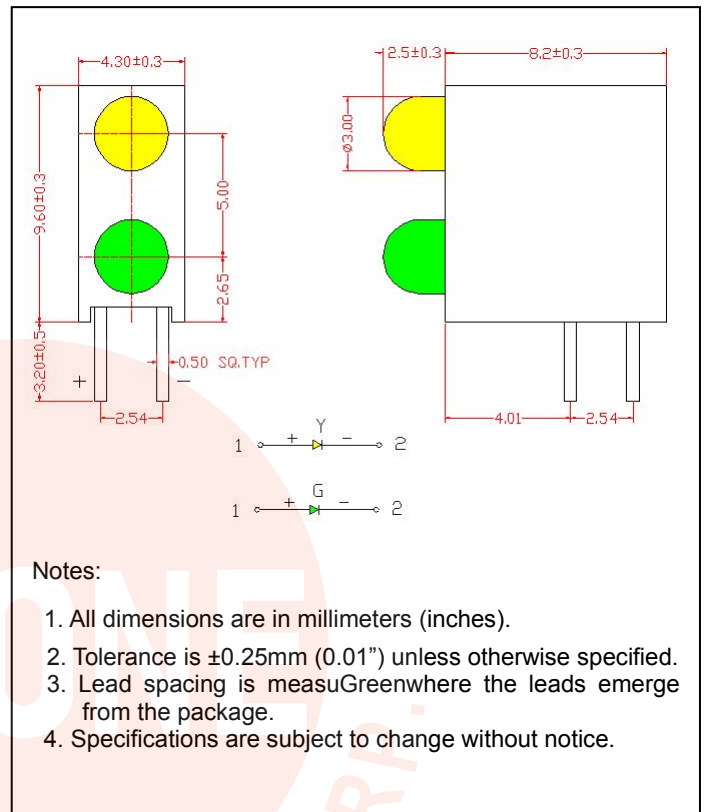
● Features:

1. Chip material: AlInGaP(Yellow)
and GaP (Green)
2. Emitted color : Yellow and Green
3. Lens Appearance : Yellow Diffused
and Green Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
8. 3mm diameter package.
9. This product don't contained restriction
substance, compliance ROHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions



● Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Yellow	Green	Unit
Power Dissipation	Pd	75	75	mW
Forward Current	I _F	30	30	mA
Peak Forward Current*1	I _{FP}	150	150	mA
Reverse Voltage	V _R	5		V
Operating Temperature	Topr	-30°C ~ 80°C		
Storage Temperature	Tstg	-40°C ~ 85°C		
Soldering Temperature	Tsol	260°C (for 5 seconds)		

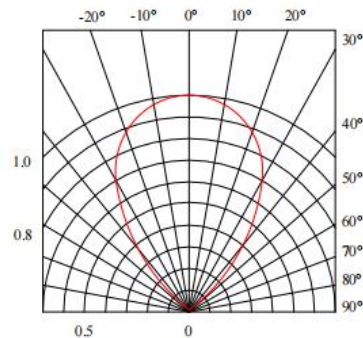
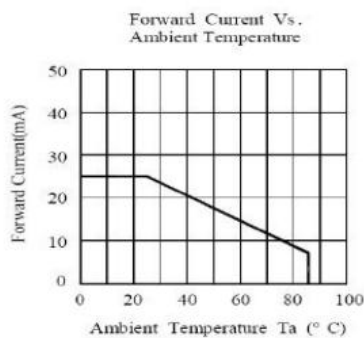
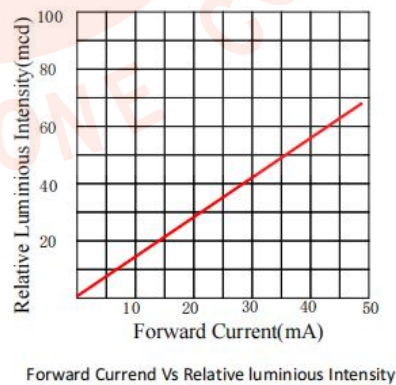
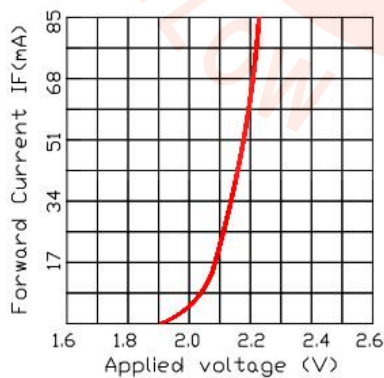
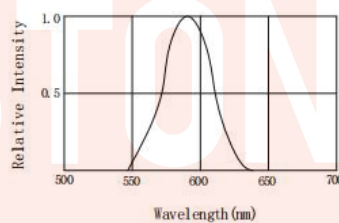
*1 Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25°C)

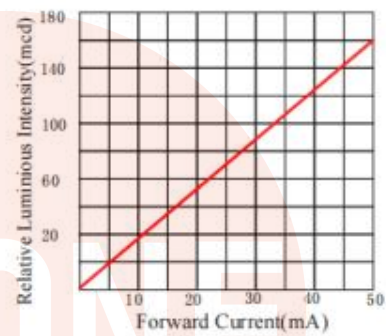
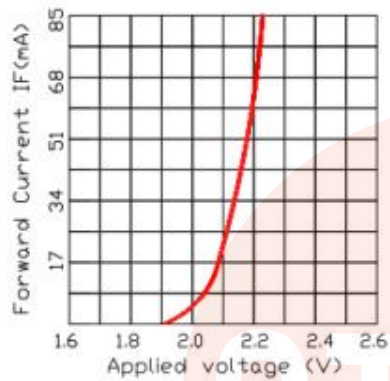
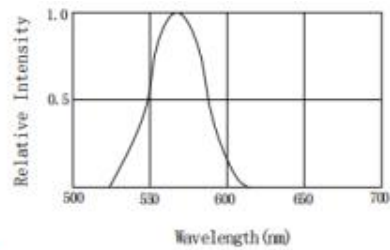
Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	Yellow Green	1.8 1.8		2.4 2.6	V
Luminous Intensity	I_v	$I_F=20\text{mA}$	Yellow Green	20 40		80 80	mcd
Reverse Current	I_R	$V_R=5\text{V}$	Yellow Green	- -	- -	10 10	μA
Peak Wave Length	λ_p	$I_F=20\text{mA}$	Yellow Green	- -	- -	- -	nm
Dominant Wave Length	λ_d	$I_F=20\text{mA}$	Yellow Green	585 565	590 570	595 575	nm
Spectral Line Half-width	$\Delta\lambda$	$I_F=20\text{mA}$	Yellow Green	- -	30 30	- -	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	Yellow Green	- -	70 50	- -	deg

● Typical Electro-Optical Characteristics Curves

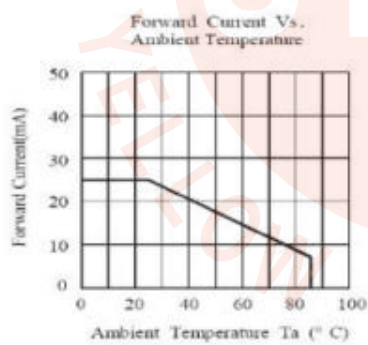
Yellow



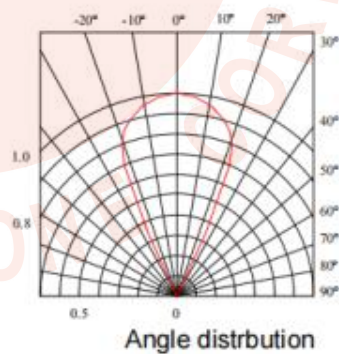
Green



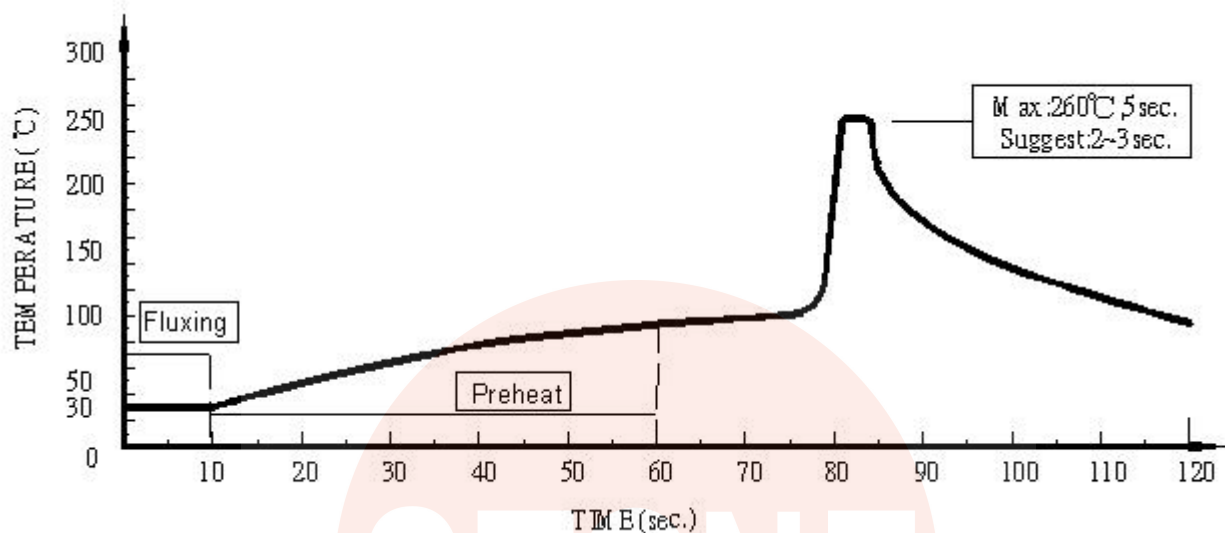
Forward Current Vs Relative luminous Intensity



Forward Current Vs. Ambient Temperature



●Dip Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

●IRON Soldering

A : Max : 350°C Within 3 sec. One time only.

B : The products of 3mm without flange, welding condition of flat plate PCB Max : 350°C Within 2 sec. One time only

